IN THE SPECIFICATION:

On page 5, please amend the last paragraph beginning on line 16, as follows:

--Fig. 1 is a schematic diagram showing the formation of metal wire patterns including a main fine line pattern120, which has to be protected from corrosion, connected to large pad patterns 100 in accordance with a first embodiment of the present invention. After the CMP process of the wire patterns, the corrosion of the main fine line pattern 120 is caused when the main fine line pattern 120, ~~when~~ having a width ~~of the main fine line pattern is~~ below 1 μm, is connected to the large pad patterns 100. When an area ratio of the main fine line pattern 120 to the entire wire patterns including the large pad patterns 100, connection pad pattern 110 and the main fine line pattern 120 is approximately above 1%, the corrosion can be prevented. A formula for preventing the corrosion is as follows:

$$(A/Ap+Ac+A)) \times 100 > 1\%$$

where, 'A' represents an area of the main fine line pattern 120, 'Ap' represents a gross area of the large pad patterns 100 and 'Ac' represents a gross area of the connection pad patterns. As shown in Fig. 1, the width of each connection pad pattern is in a range between the width of the large pad pattern and the width of the fine line pattern.--

On page 7, please amend the first full paragraph, beginning on line 7, as follows:

--Fig. 3 is a schematic diagram showing a formation of metal wire patterns using dummy fine line patterns 340 connected to large dummy pad patterns 330 for preventing the

corrosion of a main fine line pattern 320 in accordance with a third embodiment ~~of the present invention~~ of the present invention. The dummy fine line patterns have a submicron width and are formed parallel with the main fine line pattern. The large dummy pad patterns 330 and the dummy fine line patterns 340 do not make any electric circuit.--